#### TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# **T6K01**

1

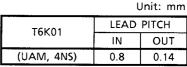
#### COLUMN DRIVER LSI FOR A DOT MATRIX GRAPHIC LCD

The T6K01 is a column (segment) driver for a dot matrix graphic LCD. The T6K01 offers low power consumption, due to the CMOS Si-Gate process. It is designed to interface directly with a microprocessor unit (MPU). A program running on the MPU can drive the T6K01 asynchronously. The T6K01 stores data transferred from the MPU in its built-in RAM.

The data stored in the built-in display RAM corresponds to the image on the LCD screen; the data is converted into the LCD drive signal. A configuration of two T6K01s and one T6C03 can be used to drive a  $480 \times 160$ -dot LCD.

#### **Features**

- Dot matrix graphic LCD column driver with display RAM
- Display RAM capacity: 160 lines × 240 outputs = 38400 bits
- LCD drive output: 240
- Interface: 8-bit MPU
- Relation between RAM data and display RAM bit data = 1 → display ON RAM bit data = 0 → display OFF
- Display OFF function
- Low power consumption
- Logic power supply: 2.7 to 3.3 V
- LCD power supply: 8.0 to 26.0 V
- CMOS Process
- Package: TCP (Tape Carrier Package)

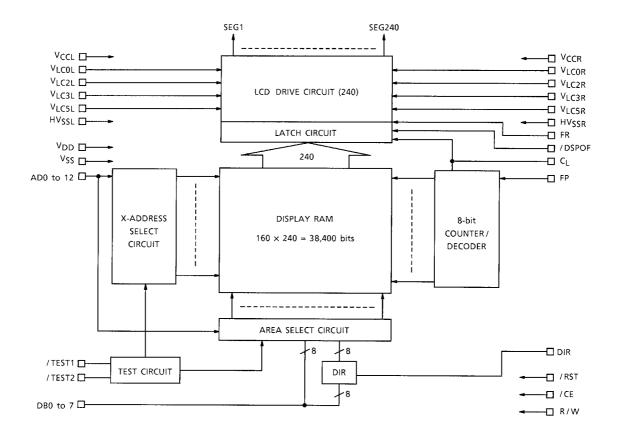


Please contact Toshiba or an authorized Toshiba dealer for information on package dimensions.

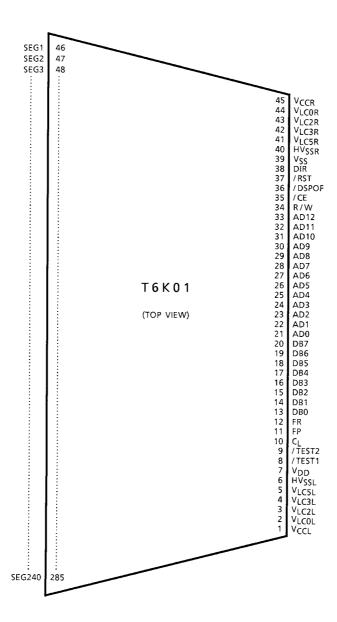
TCP (Tape Carrier Package)



# **Block Diagram**



# **Pin Assignment**



Note: The above diagram shows the pin configuration of the LSI chip; it does not show the configuration of the tape carrier package.



# **Pin Functions**

Pin Name	Pin No.	1/0	Functions			
SEG1 to SEG240	46 to 285	Output	Column driver outputs			
C <sub>L</sub>	10	Input	Shift clock pulse			
FP	11	Input	Display synchronous signal			
FR	12	Input	Frame signal			
DB0 to DB7	13 to 20	1/0	Data bus			
AD0 to AD12	21 to 33	Input	Address bus			
R/W	34	Input	Read / write select R / W = H → Read selected R / W = L → Write selected			
/ CE	35	Input	chip enable Data write: Data write enabled on rising edge of / CE Data read: Data read out while / CE is at L level			
/ DSPOF	36	Input	Display off. Usually connected to V <sub>DD</sub> .  / DSPOF = H: Display-on mode. (SEG1 to SEG240) are operational.  / DSPOF = L: Display-off mode. (SEG1 to SEG240) are at the V <sub>SS</sub> level.			
/ RST	37	Input	Reset signal: / RST = L → Reset state			
DIR	38	Input	Data direction select			
/ TEST1, 2	8, 9	Input	Test pin. Usually connected to V <sub>DD</sub>			
$V_{DD}, V_{SS}$	7, 39	_	Power supply			
VCCL, VCCR VLC0L, VLC0R VLC2L, VLC2R VLC3L, VLC3R VLC5L, VLC5R HVSSL, HVSSR	1, 45 2, 44 3, 43 4, 42 5, 41 6, 40	_	Power supply for LCD drive			

#### **Function of Each Block**

#### RAM cell

The RAM capacity is 160 lines  $\times$  240 outputs for a total of 38400 bits.

#### DIR

This circuit changes the data flow direction and page selection sequence.

#### • Address decoder

This decoder selects one RAM address for read / write operation.

#### • 8-bit counter + decoder

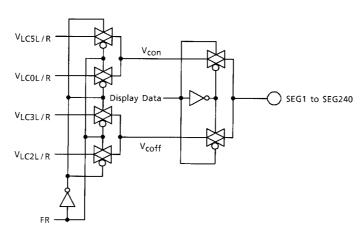
The decoder selects one RAM cell from the 160 address lines for display operation.

#### • Latch

The data is latched from the display RAM on the falling edge of CL.

#### • Column driver circuit and LCD voltage generation circuit

The T6K01 has 240 column drivers and four different LCD drive output voltage levels. The display data from the latch circuit and the M signal determine which of the four LCD drive voltages is selected. This circuit is shown in the following diagram.



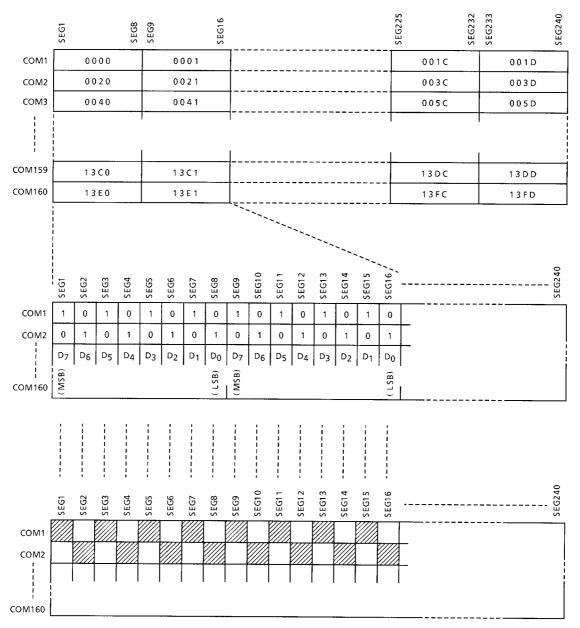
#### Relation Between FR, Data Input and Output Level

/ DSPOF	FR	Input Data (RAM Data)	Output Level
L	*	*	V <sub>SS</sub> / V <sub>LC5</sub>
Н	L	L	$V_{LC3}$
Н	L	Н	$V_{SS}/V_{LC5}$
Н	Н	L	$V_{LC2}$
Н	Н	Н	$V_{LC0}$

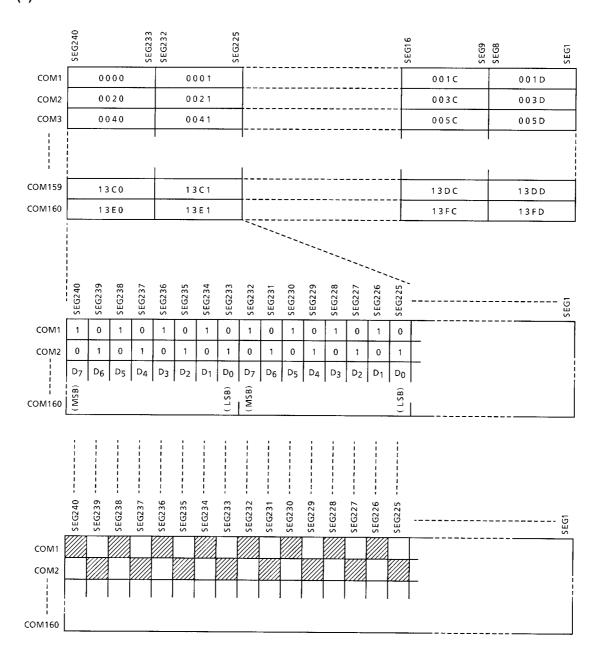
\*: INVALID

#### • The relation between DIR and the memory map

### (1) DIR = H



# (2) DIR = L



7

# Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Rating	Unit
Supply Voltage (1)	V <sub>DD</sub> (Note 2)	-0.3 to 6.5	V
Supply Voltage (2)	(Note 1, 2)	-0.3 to 28.0	V
Input Voltage	V <sub>IN</sub> (Note 2, 3)	-0.3 to V <sub>DD</sub> +0.3	٧
Operating Temperature	T <sub>opr</sub>	−20 to 75	°C
Storage Temperature	T <sub>stg</sub>	-55 to 125	°C

Note 1:  $V_{CCL}$ ,  $V_{CCR}$ ,  $V_{LC0L}$ ,  $V_{LC0R}$ ,  $V_{LC2L}$ ,  $V_{LC2R}$ ,  $V_{LC3L}$ ,  $V_{LC3R}$ ,  $V_{LC5L}$  and  $V_{LC5R}$ 

Note 2: Referenced to  $V_{SS}$ ,  $HV_{SSL}$  and  $HV_{SSR}$  Note 3: Applies to all data bus and I / O pins.

Note 4: Ensure that the following condition is always maintained.

 $V_{CCL \ / \ R} \geq V_{LC0L} \ / \ R \geq V_{LC2L} \ / \ R \geq V_{LC3L \ / \ R} \geq V \ _{LC5L \ / \ R} \geq HV_{SSL \ / \ R}$ 

8

# Electrical Characteristics DC Characteristics Test Conditions (Unless Otherwise Noted, $V_{SS}$ = 0 V, $V_{DD}$ = 3.0 V ± 10%, $V_{CCL/R}$ = 23.0 V ± 10%, $T_{AB}$ = -20 to 75°C)

Item		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit	Pin Name
Operating	Supply (1)	$V_{DD}$	_	_	2.7	_	3.3	V	$V_{DD}$
Operating	Supply (2)	V <sub>CC</sub>	_	_	8.0	_	26.0	V	V <sub>CCL</sub> , V <sub>CCR</sub>
	H Level	V <sub>IH</sub>	_	_	0.7 V <sub>DD</sub>	_	V <sub>DD</sub>	٧	DB0 to DB7 AD0 to AD7,
Input Voltage	L Level	$V_{IL}$	_	_	0		0.3 V <sub>DD</sub>	>	/ RST, / DSPOF, / CE, R / W, D / I, C <sub>L</sub> , FP, FR, DIR, / TEST
Output	Output H Level V <sub>OH</sub> — I <sub>OH</sub> = -400 μA		V <sub>DD</sub> -0.4	_	V <sub>DD</sub>	>	DB0 to DB7		
Voltage	L Level	V <sub>OL</sub>	_	Ι <sub>ΟL</sub> = 400 μΑ	V <sub>SS</sub>	_	0.4	٧	DB0 to DB1
Column Driver Output Resistance		R <sub>col</sub>	_	Load current = ±100 μA (Note 4)	_	_	3.0	kΩ	SEG1 to SEG160
Input Leakage		I <sub>IL</sub>	_	$V_{IN} = V_{DD}$ to $V_{SS}$	-1	_	1	μΑ	DB0 to DB7 AD0 to AD7, / RST, / DSPOF, / CE, R / W, D / I, C <sub>L</sub> , FP, FR, DIR, / TEST
Operating	Freq.	f <sub>CL</sub>	_	_	10	_	50	kHz	C <sub>L</sub>
Current Consumption (1)		I <sub>SS1</sub>	_	(Note 1)	_	410	520	μA	V <sub>SS</sub> , HV <sub>SSL</sub> , HV <sub>SSR</sub> , V <sub>LC5L</sub> , V <sub>LC5R</sub>
Current Consumption (2)		I <sub>SS2</sub>	_	(Note 2)	_	45	65	μA	V <sub>SS</sub> , HV <sub>SSL</sub> , HV <sub>SSR</sub> , V <sub>LC5L</sub> , V <sub>LC5R</sub>
Current Consumption (3)		lss3	_	(Note 3)	-1	_	1	μA	V <sub>SS</sub> , HV <sub>SSL</sub> , HV <sub>SSR</sub> , V <sub>LC5L</sub> , V <sub>LC5R</sub>

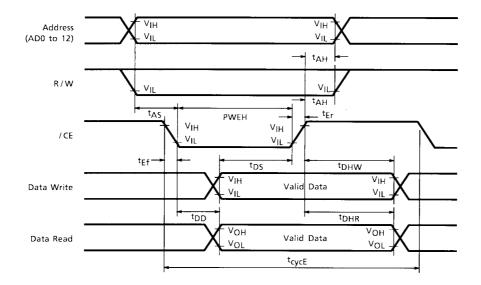
Note 1: Current consumption while internal data receiver is operating  $V_{DD}$  = 3.0 V ±10%,  $V_{CCL}$  / R = 23.0 V, Ta = 25°C, 1 / 13 bias, 1 / 160 duty, no load,  $f_{FP}$  = 70 Hz,  $f_{CE}$  = 5 MHz

Note 2: Current consumption while internal data receiver is sleeping  $V_{DD}$  = 3.0 V ±10%,  $V_{CCL/R}$  = 23.0 V, Ta = 25°C, 1 / 13 bias, 1 / 160 duty, no load, f<sub>FP</sub> = 70 Hz, f / CE = 0 Hz

Note 3: Standby current consumption  $V_{DD}$  = 3.0 V ±10%,  $V_{CCL/R}$  = 23.0 V, Ta = 25°C, no load,  $f_{FP}$  = 0 Hz,  $f_{/CE}$  = 0 Hz

Note 4:  $V_{CCL/R} = V_{LC0L/R} = 23.0 \text{ V}$ ,  $V_{LC2L/R} = V_{CC} \times 11 / 13$ ,  $V_{LC3L/R} = V_{CC} \times 2 / 13$ ,  $HV_{SSL/R} = V_{LC5L/R} = 0 \text{ V}$ 

# **AC Characteristics (1)**



Test Conditions (Unless Otherwise Noted,  $V_{SS}$  = 0 V,  $V_{DD}$  = 3.0 V ±10%, Ta = -20 to 75°C)

Item	Symbol	Min	Max	Unit
Enable Cycle Time	t <sub>cycE</sub>	250	_	ns
Enable Pulse Width	PWEH	160	_	ns
Enable Rise / Fall Time	t <sub>Er</sub> , t <sub>Ef</sub>	_	20	ns
Address Set-up Time	t <sub>AS</sub>	0	_	ns
Address Hold Time	t <sub>AH</sub>	10	_	ns
Data Set-up Time	t <sub>DS</sub>	100	-	ns
Data Hold Time	t <sub>DHW</sub>	20	-	ns
Data Delay Time	t <sub>DD</sub> (Note)	_	180	ns
Data Hold Time	t <sub>DHR</sub> (Note)	20	_	ns

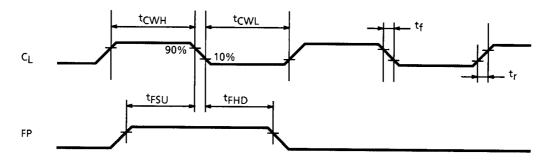
#### **Load Circuit**

C = 40 PF
(including wiring capacitance)

Note: With load circuit connected

# **AC Characteristics (2)**

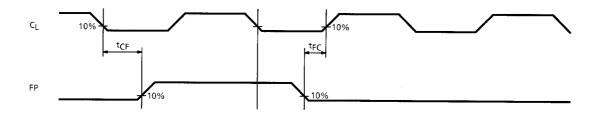
display data



Test Conditions (Unless Otherwise Noted,  $V_{SS}$  = 0 V,  $V_{DD}$  = 3.0 V  $\pm$  10%, Ta = -20 to 75°C)

Item	Symbol	Pin Name	Min	Max	Unit
C <sub>L</sub> Pulse Width H	t <sub>CWH</sub>	CL	500	_	ns
C <sub>L</sub> Pulse Width L	t <sub>CWL</sub>	CL	500	_	ns
C <sub>L</sub> Rise / Fall Time	t <sub>r</sub> , t <sub>f</sub>	CL	_	50	ns
FP Set-up Time	t <sub>FSU</sub>	FP	100	_	ns
FP Hold Time	t <sub>FHD</sub>	FP	100	_	ns

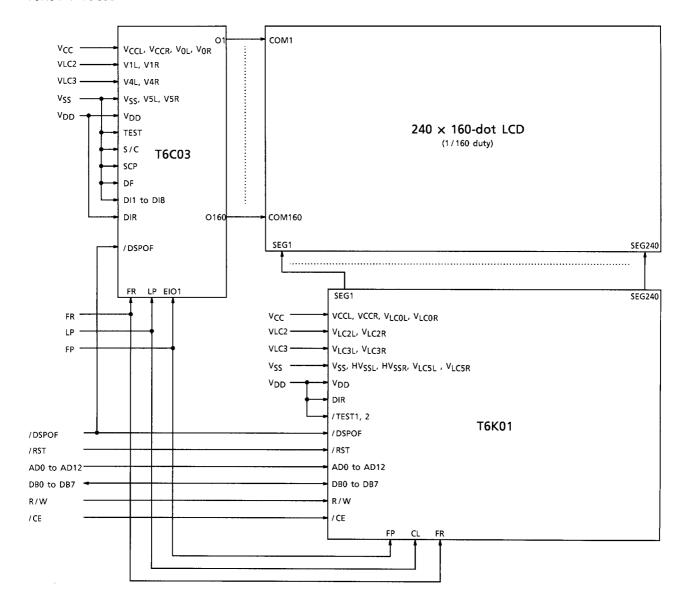
# **AC Characteristics (3)**



Item	Symbol	Condition	Min	Max	Unit
C <sub>L</sub> -to-FP-margin time	t <sub>CF</sub>		20	-	ns
FP-to-C <sub>L</sub> -margin time	t <sub>FC</sub>		0	_	ns

# **Application Circuit**

T6K01 + T6C03



#### **RESTRICTIONS ON PRODUCT USE**

000707EBE

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- Polyimide base film is hard and thin. Be careful not to injure yourself on the film or to scratch any other parts with
  the film. Try to design and manufacture products so that there is no chance of users touching the film after
  assembly, or if they do, that there is no chance of them injuring themselves. When cutting out the film, try to
  ensure that the film shavings do not cause accidents. After use, treat the leftover film and reel spacers as
  industrial waste.
- Light striking a semiconductor device generates electromotive force due to photoelectric effects. In some cases this can cause the device to malfunction.
  - This is especially true for devices in which the surface (back), or side of the chip is exposed. When designing circuits, make sure that devices are protected against incident light from external sources. Exposure to light both during regular operation and during inspection must be taken into account.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- The information contained herein is presented only as a guide for the applications of our products. No
  responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other
  rights of the third parties which may result from its use. No license is granted by implication or otherwise under
  any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.